# **1000 MHz Quadrature Demodulator**

### Description

U2794B silicon monolithic integrated circuit is a quadrature demodulator that is manufactured using TELEFUNKEN's advanced UHF technology. This demodulator features a frequency range from 70 - 1000 MHz, low current consumption, selectable

Features

- Supply voltage 5 V (typ.)
- Very low power consumption 125 mW (typ.)
- Very good image rejection by means of phase control loop for precise 90° phase shifting
- Duty cycle regeneration for single ended LO input signal

gain, power down mode and is adjustment free. The IC is suitable for direct conversion and image rejection applications in digital radio systems up to 1 GHz such as cellular radio, cordless telephone, cable TV and satellite TV systems.

- Low LO input level –10 dBm (typ.)
- LO frequency from 70 MHz to 1 GHz
- Power down mode
- 25 dB gain control
- Very low I/Q output dc offset voltage typ. < 5 mV



### **Block Diagram**

### **Ordering Information**

Extended Type Number	Package	Remarks
U2794B-AFS	SSO 20	Rail, MOQ 830 pcs.
U2794B-AFSG3	SSO 20	Tape and reel, MOQ 4000 pcs.

# U2794B

## **Pin Description**



Pin	Symbol	Function
1	IX	IX output
2	Ι	I output
3	II	II low pass filter I
4	IIX	IIX low pass filter I
5	Vs	Supply voltage
6	Vs	Supply voltage
7	RF <sub>in</sub>	RF input
8	RFX <sub>in</sub>	RFX input
9	QQ	QQ low pass filter Q
10	QQX	QQX low pass filter Q
11	GC	GC gain control
12	PCX	PCX phase control
13	PC	PC phase control
14	PD	PD power down
15	LOX <sub>in</sub>	LOX input
16	GND	Ground
17	LO <sub>in</sub>	LO input
18	GND	Ground
19	Q	Q output
20	QX	QX output

### Electrostatic sensitive device, observe precautions for handling!

# **Absolute Maximum Ratings**

Parameters		Symbol	Value	Unit
Supply voltage	Pins 5 and 6	Vs	6	V
Input voltage	Pins 7, 8 and 17	Vi	0 to V <sub>S</sub>	V
Junction temperature		Tj	125	°C
Storage temperature	range	T <sub>stg</sub>	-40 to 125	°C

# **Operating Range**

Parameters	Symbol	Value	Unit
Supply voltage range Pins 5 and 6	Vs	4.75 to 5.25	V
Ambient temperature range	T <sub>amb</sub>	-40 to 85	°C

### **Thermal Resistance**

Parameters	Symbol	Value	Unit
Junction ambient SSO 20	R <sub>thJA</sub>	140	K/W

# **Electrical Characteristics**

Test conditions (unless otherwise specified);  $V_S = 5 \text{ V}$ ,  $T_{amb} = 25^{\circ}\text{C}$ , referred to test circuit System impedance  $Z_O = 50 \Omega$ , fiLO = 950 MHz, PiLO = -10 dBm

Parameters	Test Con	ditions / Pins	Symbol	Min.	Тур.	Max.	Unit
Supply voltage range		Pins 5 and 6	Vs	4.75		5.25	V
Supply current		Pins 5 and 6	IS		30		mA
Power down mode, PD							
"OFF"mode supply current	$\label{eq:VPD} \begin{array}{c} V_{PD} \leq 0.5 \ V \\ V_{PD} = 1.0 \ V \\ Note \ 1 \end{array}$	Pins 5 and 6 Pin 14	IsPD		≤ 1 20		μΑ
Switch voltage		Pin 14					
"Power ON"			VPON	4			V
"Power DOWN"			VPOFF			1	V
LO input, LO <sub>in</sub>		Pin 17					
Frequency range			fiLO	70		1000	MHz
Input level	Note 2		PiLO	-12	-10	-5	dBm
Input impedance	See figure 6		ZiLO		50		Ω
Voltage standing wave ratio	See figure 2		VSWRLO		1.2	2	
Duty cycle range			LODCR	0.4		0.6	
RF input, RF <sub>in</sub>	•						
Noise figure (DSB) symmetrical output	@ 950 MHz @ 100 MHz	Note 3 Pins 7 and 8	NF		12 10		dB
Frequency range		Pins 7 and 8	fiRF			>fiLO	
-1 dB input compression point	High gain Low gain	Pins 7 and 8	ICPHG ICPLG		-8 +3.5		dBm
Second order IIP	Note 4	Pins 7 and 8	IIP2HG		35		dBm
Third order IIP	High gain Low gain	Pins 7 and 8	IIP3HG IIP3LG		+3 +13		dBm
LO leakage	Symmetric in Asymmetric		LOL		$\leq -60$ $\leq -55$		dBm
Input impedance	see figure 6	Pins 7 and 8	ZiRF		500Ω∥ 0.8pF		

Note 1: During power down status a load circuitry with dc-isolation to GND is assumed otherwise a current of  $I \approx (V_S - 0.8 \text{ V}) / \text{RI}$  has to be added to the above power down current for each output I, IX, Q, QX.

Note 2: The required LO-Level is a function of the LO-frequency (see figure 3).

Note 3: Measured with input matching. For 950 MHz the optional transmission line T3 at the RF input may be used for this purpose. Noise figure measurements without using the differential output signal result in a worse noise figure.

Note 4: Using Pins 7 and 8 as a symmetric RF input, the second order IIP can be improved.

# **Electrical Characteristics**

Test conditions (unless otherwise specified);  $V_S = 5$  V,  $T_{amb} = 25^{\circ}C$ , referred to test circuit System impedance  $Z_O = 50 \Omega$ , fiLO = 950 MHz, PiLO = -10 dBm

Parameters	Test Conditions / Pins	Symbol	Min.	Тур.	Max.	Unit
I/O outputs	Emitter follower $I = 0.6 \text{ mA}$	I, IX / Q, QX				
3 dB-bandwidth w/o external C	Note 5 Pins 1, 2, 19 and 20	BWI/Q	≥ 30			MHz
I/Q amplitude imbalance	Pins 1, 2, 19 and 20	AII/Q		≤±0.2		dB
I/Q quadrature error	Pins 1, 2, 19 and 20	QEI/Q		$\leq \pm 1.5$		Deg
I/Q maximum output swing	Pins 1, 2, 19 and 20 Symm. output $R_L > 5 k\Omega$	Max I/Q			2	V <sub>PP</sub>
DC output voltage	Pins 1, 2, 19 and 20	VOUT		2.8		V
DC output offset voltage	Note 6 Pins 1, 2, 19 and 20	VOFSI/Q I/IX Q/QX		< 5		mV
Output impedance	Pins 1, 2, 19 and 20 see figure 6	Zout		50		Ω
Gain control, GC		·		•		
Control range power gain, gain high/gain low	Pin 11 Note 7	GCR PGH/GGL		25 23/–2		dB
Switch voltage						
"Gain high"	Pin 11	GCVHigh			1	V
"Gain low"	Note 8 Pin 11	GCVLow				V
Settling time, ST						
Power "OFF" – "ON"		STON		< 4		μs
Power "ON" – "OFF"		STOFF		< 4		μs

Note 5: Due to test board parasitics this bandwidth is reduced and not equal for I, IX, Q, QX. If symmetry and full bandwidth is required the lowpass Pins 3, 4 and 9, 10 should be isolated from the board. The bandwidth of the I/Q outputs can be increased further by using a resistor between the Pins 3, 4, 9 and 10. This resistors shunt the internal loads of RI ~ 5.4 kΩ The decrease in gain here has to be considered.

Note 6: Output emitter follower internal acurrent I = 0.6 mA allows only small voltage swing with a 50  $\Omega$  load. For low signal distortion the load impedance should be RI  $\ge$  5 k $\Omega$ 

Note 7: Referred to the level of the output vector  $\sqrt{I^2 + Q^2}$ .

Note 8: The low gain status is achieved with an open or high ohmic Pin 11. A recommended application circuit for switching between high and low gain status is shown in figure 1.

## **Test Circuit**



\* optional for single ended tests (notice 3 dB bandwidth of AD620)

T1, T2 = transmission line  $Z_0 = 50 \Omega$ .

If no GC function is required, connect pin 11 to GND.

For high and low gain status GC' is to be switched to GND respectively to V<sub>S</sub>.

Figure 1.

# U2794B

#### 

Figure 2. Typical VSWR frequency response of the LO input



Figure 3. Typical suitable LO power range vs. frequency



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Figure 4. Noise figure vs. LO frequency; o: value at 950 MHz with RF input matching with T3



Figure 5. Gain vs. LO frequency; x: value at 950 MHz with RF input matching with T3

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Figure 6. Typical S11 frequency response of the a: LO input, LO frequency from 100 MHz to 1100 MHz, marker: 950 MHz b: RF input, RF frequency from 100 MHz to 1100 MHz, marker: 950 MHz c: I/Q outputs, baseband frequency from 5 MHz to 55 MHz, marker: 25 MHz

# U2794B

# TELEFUNKEN Semiconductors

# **Board Layout**



95 9854

### **Board Layout**



### **External Components**

CUCC 100 nF CRFX 1 nF CLO 100 pF CNLO1 nF CRF 100 pF CII, CQQ optional external lowpass filters T3 transmission line for RF-input matching, to connect optionally CI, CIX, optional for ac-coupling at CQ, CQX baseband outputs CPDN 100 pF CGC 100 pF CPC 100 pF CNPC 100 pF GSW gain switch

### **Calibration Part**

CO, CS, CL 100 pF RL 50 Ω

### **Conversion to Single Ended Output**

OP1, OP2 RG1, RG2	AD620 prog. gain, see datasheet, for 5.6 k $\Omega$ a gain of 1 at 50 $\Omega$ is achieved together with RD1 and RD2.
RD1, RD2	450 Ω
CS1, CS2	100 nF
CS3, CS4,	100 nF

Rev. A3: 23.08.1995

### **Description of Evaluation Board**

Board material:

epoxy;  $\epsilon r = 4.8$ , thickness = 0.5 mm transmission lines:  $Z_{O} = 50 \Omega$ 

#### The board offers the following functions

- The test circuit for the U2794B:
- The supply voltage and the control inputs GC, PC and PD are connected via a plug strip. The control input voltages can be generated via external potentiometers; then the inputs should be ac-grounded (time requirements in burst-mode for power up have to be considered).
- The outputs I, IX, Q, QX are dc coupled via an plug strip or can be ac-connected via SMB plugs for high frequency tests e.g. noise figure or s-parameter measurement. The pins II, IIX, QQ, QQX allow user definable filtering with 2 external capacitors CII, CQQ.
- Also the offsets of both channels can be adjusted with two potis or resistors.

- The LO- and the RF-inputs are ac-coupled and connected via SMB plugs. If transmission line T3 is connected to the RF-input and ac-grounded at the other end, gain and noise performance can be improved (input matching to 50 Ω).
- The complementary RF-input is ac-coupled to GND (CRFX = 1 nF), the same appears to the complementary LO-input (CNLO = 1 nF).
- A calibration part, which allows to calibrate an s-parameter analyzer directly to the in- and output-signal ports of the U2794B.
- For single-ended measurements at the demodulator outputs, two OP's (e.g., AD620 or other) can be configured with programmable gain; together with an output-divider network RD = 450  $\Omega$  to RL = 50  $\Omega$ , direct measurements with 50  $\Omega$  load-impedances are possible at frequencies < 100 kHz.

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### **Dimensions in mm**

Package: SSO 20

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- 2. Regularly and continuously improve the performance of our products, processes, distribution and operating systems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

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